

ADHESIVE SHEET FOR BACKGRINDING AND PRODUCTION METHOD FOR SEMICONDUCTOR WAFER

Abstract

Provided is an adhesive sheet for backgrinding which enables sufficient backgrinding while protecting protrusions provided on a semiconductor wafer. The present invention provides an adhesive sheet for the backgrinding of a semiconductor wafer that has protrusions, said adhesive sheet being characterized by comprising a non-adhesive cushion layer and an adhesive layer provided on the cushion layer, with a curable resin and a support film being layered on the cushion layer side for use, wherein the viscosity of the curable resin prior to curing is 100-3000 mPa·s, the Shore D hardness of the curable resin layer subsequent to curing is 5-72, and at least one of conditions (1) and (2) is satisfied. (1) When punched in the shape of a dumbbell in accordance with JIS Z1702 and stretched by 25% at a tensioning speed of 300 mm/min with a gauge length of 40 mm, the cushion layer has a tensile stress of 2-30 N/10 mm. (2) The cushion layer is composed of a thermoplastic resin that has a melting point of 60-110°C and a melt flow rate (JIS K7210, 125°C/10.0 kg load) of 0.2-30 g/10 min.

[Figures 1A, 1B, 1C, 1D]